



Material Content Data Sheet



Sales Product Name		TLE75080-ESD		Issued		4. March 2019		
MA#		MA003348016						
Package		PG-TSDSO-24-21		Weight*		111.95 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.094	2.76	2.76	27634	27634
leadframe	inorganic material	phosphorus	7723-14-0	0.016	0.01		141	
	non noble metal	zinc	7440-66-6	0.063	0.06		565	
	non noble metal	iron	7439-89-6	1.266	1.13		11306	
wire	non noble metal	copper	7440-50-8	51.392	45.92	47.12	459058	471070
	non noble metal	copper	7440-50-8	0.764	0.68	0.68	6821	6821
	encapsulation	organic material	carbon black	1333-86-4	0.151	0.13		1344
plastics		epoxy resin	-	5.870	5.24		52432	
	inorganic material	silicondioxide	60676-86-0	44.149	39.44	44.81	394362	448138
leadfinish	non noble metal	tin	7440-31-5	2.820	2.52	2.52	25191	25191
plating	noble metal	silver	7440-22-4	1.279	1.14	1.14	11425	11425
glue	plastics	epoxy resin	-	0.190	0.17		1701	
	noble metal	silver	7440-22-4	0.898	0.80	0.97	8020	9721
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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